

FEATURES

- Narrow beam angle
- Convenient TO-5 package with leads
- Hermetic package

Dimensions are nominal values in inches unless otherwise specified.



ELECTRO-OPTICAL CHARACTERISTICS AT 25°C

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Total Power Output, P_o	$I_F = 350\text{mA}$	80	170		mW
Peak Emission Wavelength, λ_p	$I_F = 350\text{mA}$		635		nm
Spectral Bandwidth at 50%, $\Delta\lambda$			40		nm
Dominant Wavelength, λ_d				624	
Half Intensity Beam Angle, θ	$I_F = 350\text{mA}$		7		Deg
Forward Voltage, V_F	$I_F = 350\text{mA}$		2.3	3.0	Volts
Reverse Breakdown Voltage, V_R	$I_R = 5\mu\text{A}$	10			Volts

ABSOLUTE MAXIMUM RATINGS AT 25°C

Continuous Forward Current	500mA
Reverse Voltage	10V
Lead Soldering Temperature (1/16" from case for 10sec)	260°C

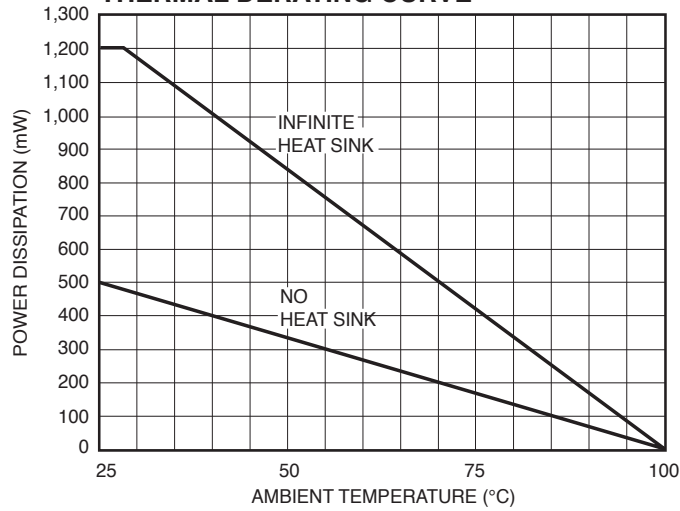
THERMAL PARAMETERS

Storage and Operating Temperature Range	-55°C TO 100°C
Maximum Junction Temperature	115°C
Thermal Resistance, R_{THJA}^1	150°C/W Typical
Thermal Resistance, R_{THJA}^2	60°C/W Typical

¹ Heat transfer minimized by measuring in still air with minimum heat conducting through leads.

² Air circulating at a rapid rate to keep case temperature at 25°C.

THERMAL DERATING CURVE



RADIATION PATTERN

